



ASE Honored by Vitesse

Supplier of the Year award testament to ASE's technology leadership and customer dedication

Santa Clara, California, August 6, 2008 – Advanced Semiconductor Engineering Incorporated (ASE, TAIEX: 2311, NYSE: ASX), the world's largest semiconductor packaging and test company, announced today that it has received a Supplier of the Year award from Vitesse Semiconductor Corporation (Pink Sheets: VTSS). Vitesse, a leading provider of advanced IC solutions for Carrier and Enterprise Networks, selected ASE for consistently providing the technology and manufacturing acumen pertinent to the successful production of its sophisticated, high-performance communication devices.

ASE received the award based on the high level of performance achieved in all criteria defined by Vitesse to measure supplier performance, including quality, delivery, technology, value, and service. A previous recipient of this award, ASE provides a broad range of services to Vitesse, encompassing full turnkey assembly and test solutions for package types including flip chip, PBGA, and HSBGA, as well as bumping. ASE also supplies substrate to Vitesse.

"The strength of the working relationships we have with vendors contributes to Vitesse achieving its strategic objectives. ASE exemplifies the qualities and services we seek," said Roy Carew, vice president of Quality for Vitesse. "ASE's integrity, agility and willingness to go above and beyond helps fuel the success of Vitesse in today's highly competitive global market, so we are pleased to recognize their efforts with this award."

"We are truly honored to receive this accolade from Vitesse, which represents a lot of dedication by ASE," said Rich Rice, senior vice president of sales, ASE Group. "Vitesse is a valued customer and we are proud to be able to bring our broad technology portfolio and leadership in innovation to help them better serve their customers."

About ASE Group

The ASE Group is the world's largest provider of independent semiconductor manufacturing services in assembly and test. As a global leader geared towards meeting the industry's ever growing needs for faster, smaller and higher performance chips, the Group develops and offers a wide portfolio of technology and solutions including IC test program

design, front-end engineering test, wafer probe, wafer bump, substrate design and supply, wafer level package, flip chip, system-in-package, final test and electronic manufacturing services through Universal Scientific Industrial Co Ltd, a member of the ASE Group. The Group generated sales revenues of \$3.1 billion in 2007 and employs over 28,000 people worldwide. For more information about the ASE Group, visit www.aseglobal.com.

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